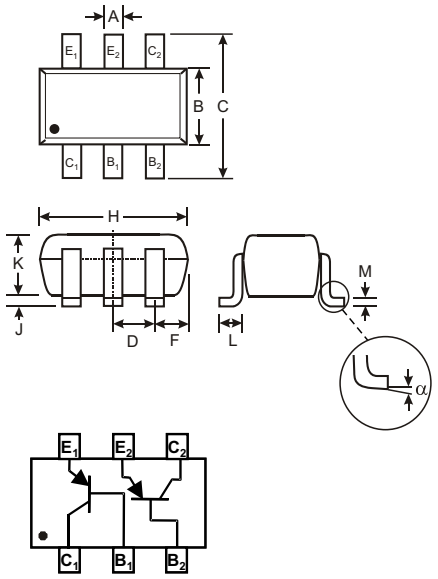
DMMT5401

MATCHED PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

- Epitaxial Planar Die Construction
- Complementary NPN Type Available (DMMT5551)
- Ideal for Low Power Amplification and Switching
- Intrinsically Matched PNP Pair (Note 1)
- 2% Matched Tolerance, h_{FE}, $V_{CE(SAT)}$, $V_{BE(SAT)}$
- **Lead Free/RoHS Compliant (Note 4)**
- **"Green" Device, Note 5 and 6**



SOT-26			
Dim	**Min**	**Max**	**Typ**
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D			0.95
F			0.55
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
	0	8	
All Dimensions in mm			

Mechanical Data

- Case: SOT-26
- Case Material: Molded Plastic, "Green" Molding Compound, Note 7. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: See Diagram
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Copper leadframe).
- Marking (See Page 2): K4S
- Order & Date Code Information: See Page 2
- Weight: 0.006 grams (approximate)

Maximum Ratings @ T_A = 25 C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-160	V
Collector-Emitter Voltage	V_{CEO}	-150	V
Emitter-Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous (Note 2)	I_C	-200	mA
Power Dissipation (Note 2, 3)	P_d	300	mW
Thermal Resistance, Junction to Ambient (Note 2)	R_{JA}	417	°C/W
Operating and Storage and Temperature Range	T_j, T_{STG}	-55 to +150	C

Notes:
1. Built with adjacent die from a single wafer.
2. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
3. Maximum combined dissipation.
4. No purposefully added lead.
5. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
6. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

Electrical Characteristics @ T_A = 25 C unless otherwise specified

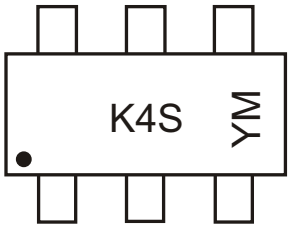
Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)					
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	-160		V	I_C = -100 A, I_E = 0
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	-150		V	I_C = -1.0mA, I_B = 0
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	-5.0		V	I_E = -10 A, I_C = 0
Collector Cutoff Current	I_{CBO}		-50 	nA A	V_{CB} = -120V, I_E = 0 V_{CB} = -120V, I_E = 0, T_A = 100 C
Emitter Cutoff Current	I_{EBO}		-50	nA	V_{EB} = -3.0V, I_C = 0
ON CHARACTERISTICS (Note 7)					
DC Current Gain (Note 8)	h_{FE}	50 60 50	240		I_C = -1.0mA, V_{CE} = -5.0V I_C = -10mA, V_{CE} = -5.0V I_C = -50mA, V_{CE} = -5.0V
Collector-Emitter Saturation Voltage	$V_{CE(SAT)}$		-0.2 -0.5	V	I_C = -10mA, I_B = -1.0mA I_C = -50mA, I_B = -5.0mA
Base-Emitter Saturation Voltage	$V_{BE(SAT)}$		-1.0	V	I_C = -10mA, I_B = -1.0mA I_C = -50mA, I_B = -5.0mA
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C_{obo}		6.0	pF	V_{CB} = -10V, f = 1.0MHz, I_E = 0
Small Signal Current Gain	h_{fe}	40	200		V_{CE} = -10V, I_C = -1.0mA, f = 1.0kHz
Current Gain-Bandwidth Product	f_T	100	300	MHz	V_{CE} = -10V, I_C = -10mA, f = 100MHz
Noise Figure	NF		8.0	dB	V_{CE} = -5.0V, I_C = -200 A, R_S = 10 f = 1.0kHz

Ordering Information (Note 6 & 9)

Device	Packaging	Shipping
DMMT5401-7-F	SOT-26	3000/Tape & Reel

Notes:
6. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.
7. Short duration pulse test used to minimize self-heating effect.
8. The DC Current Gain, h_{FE}, (matched at I_C = -10mA and V_{CE} = -5V) Collector Emitter Saturation Voltage, $V_{CE(SAT)}$, and Base Emitter Saturation Voltage, $V_{BE(SAT)}$ are matched with typical matched tolerances of 1% and maximum of 2%.
9. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



K4S = Product Type Marking Code
YM = Date Code Marking
Y = Year ex: T = 2006
M = Month ex: 9 = September

Date Code Key

Year	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	R	S	T	U	V	W	X	Y	Z

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

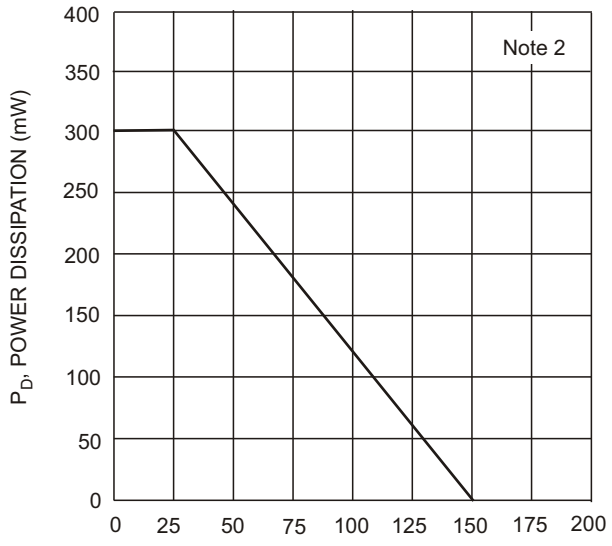


Fig. 1, Max Power Dissipation vs Ambient Temperature

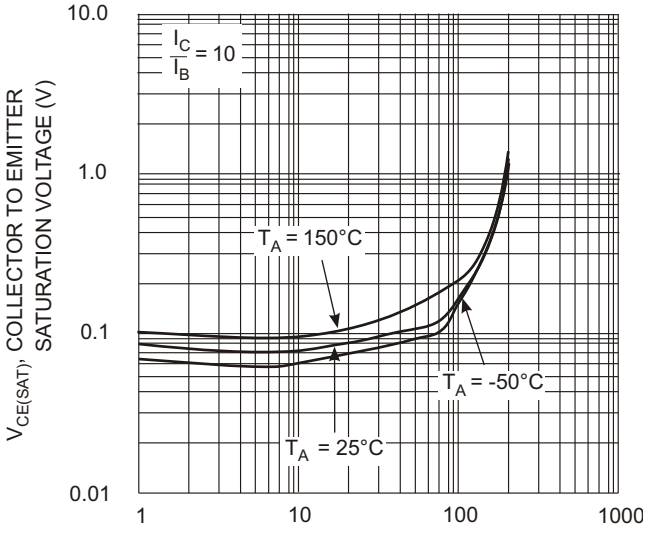


Fig. 2, Collector Emitter Saturation Voltage vs. Collector Current

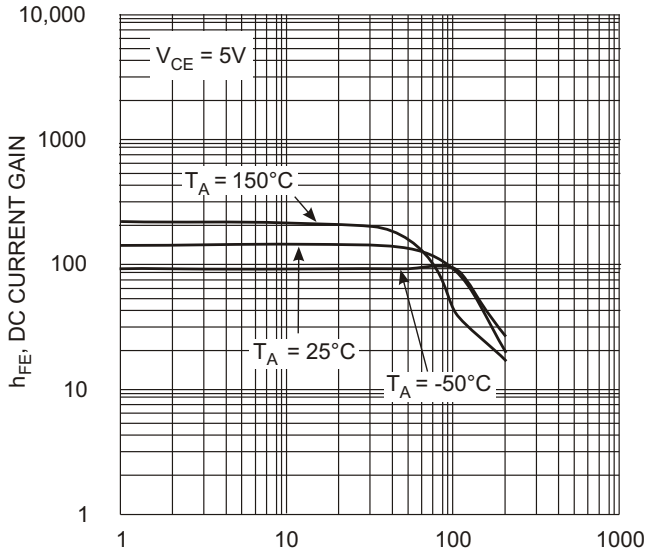


Fig. 3, DC Current Gain vs. Collector Current

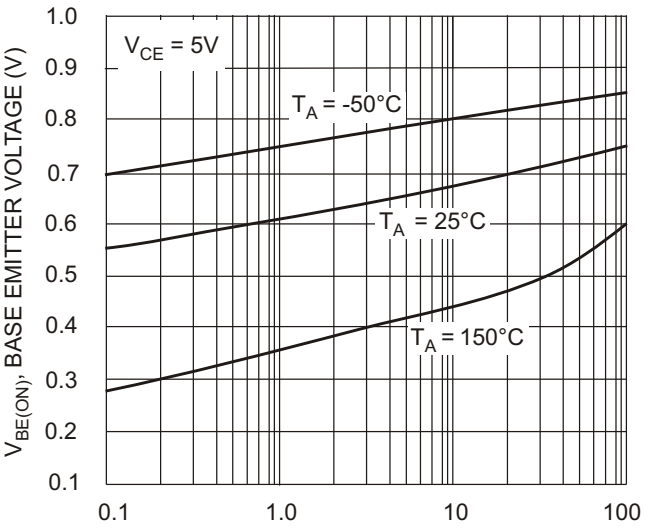


Fig. 4, Base Emitter Voltage vs. Collector Current

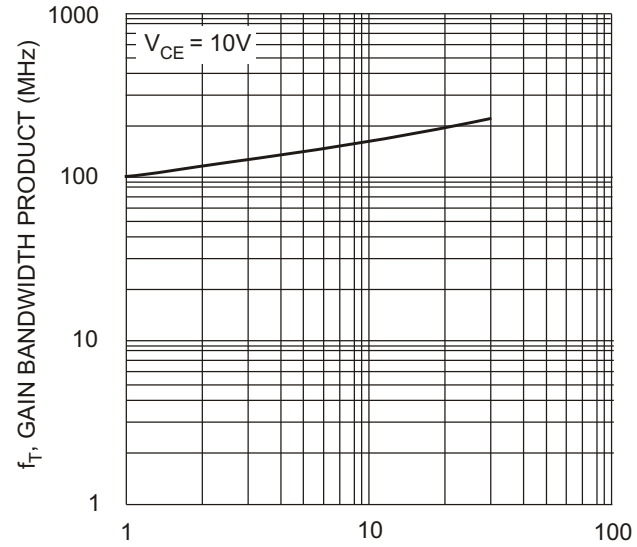


Fig. 5, Gain Bandwidth Product vs Collector Current

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